

電子飛跡検出型
コンプトンカメラによる
長時間GRB検出の可能性

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Electron-Tracking Compton Camera (ETCC)

MeV γ -ray

Drift plane

e^-

μ -PIC

incident γ

Scintillator

PMTs

recoil e

α

scattered γ

- **Gaseous TPC : Tracker**
track and energy
of recoil electron
- **Scintillator : Absorber**
position and energy
of scattered gamma



Reconstruct Compton scattering event by event

- ▶ 1 photon \Rightarrow direction + energy
- ▶ Large FOV ($\sim 3\text{str}$)
- ▶ **Kinematical background rejection**

$$\cos \alpha_{\text{geo}} = \vec{g} \cdot \vec{e} \iff \cos \alpha_{\text{kin}} = \left(1 - \frac{m_e c^2}{E_\gamma}\right) \sqrt{\frac{K_e}{K_e + 2m_e c^2}}$$

E_γ : Energy of scattered gamma-ray
 K_e : Kinematic energy of recoil electron
 $m_e c^2$: Rest mass of electron

g : unit vector of scattering direction
 e : unit vector of recoil direction

Motivation

Observation of MeV gamma-ray will provide us...

◆ Nucleosynthesis

SNR : Radio-isotopes

Galactic plane : ^{26}Al • ^{60}Fe
Annihilation

◆ Acceleration

Jet (AGN), GRB

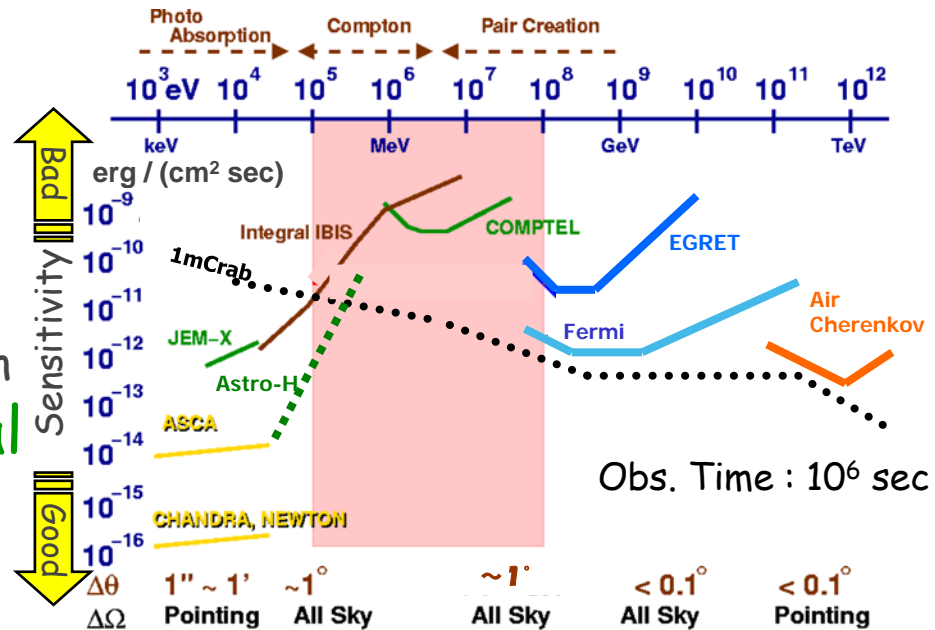
: Synchrotron + Inverse Compton

◆ Strong Gravitational Potential

Black Hole : accretion disk, π^0

◆ Etc.

Gamma-ray Pulsar, solar flare



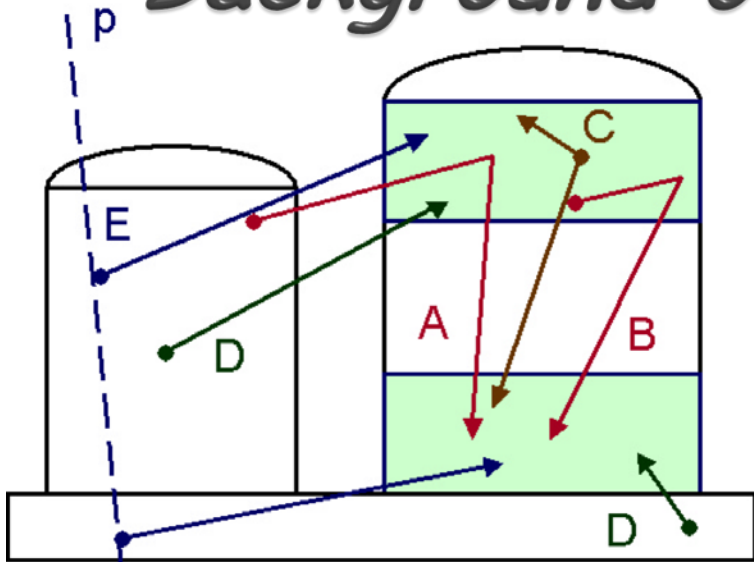
- The observation of continuum component is also important.
- Where are MeV gamma-ray objects?
- There are many background events which obstruct the observations.

Requirements for the next-generation detectors are ...

- Wide-band detection
- Large Field of View
- Background rejection

Background of COMPTTEL

G. Weidenspointner, et.al. (A&A, 2001)



A : external γ
B : internal γ } Intrinsic background

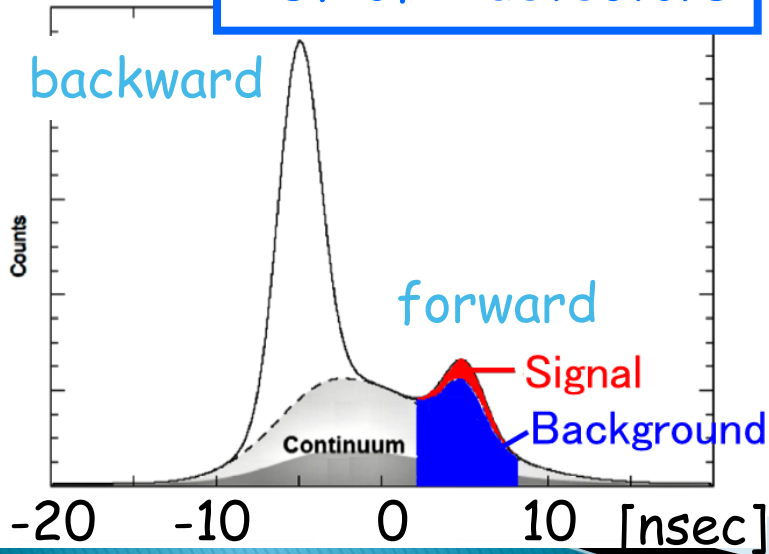
C : two γ

D : random coincidence

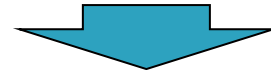
E : proton-induced γ

Other background
neutron
electron
gamma from atmosphere

TOF of 2 detectors



COMPTTEL has rejected such background by the measurement of the Time Of Flight between 2 detectors.



Background rejection was not complete
Bad S/N

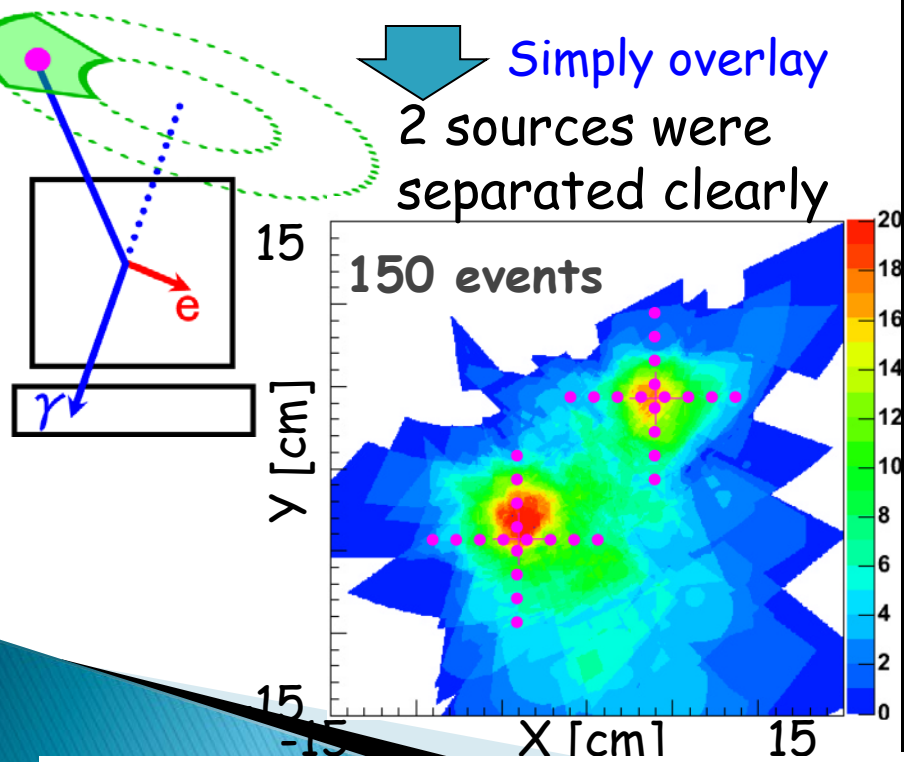
Comparison with the usual Compton method

Electron-Tracking Compton (ETCC)

Using the electron tracks

- complete direction within sector form error region

Simply overlay
2 sources were
separated clearly



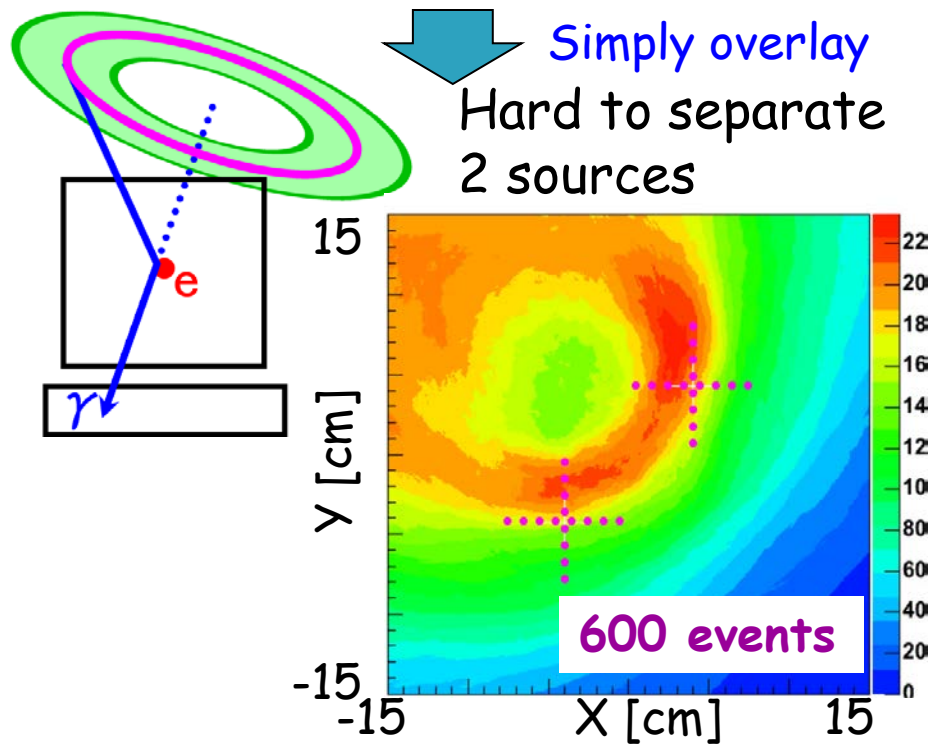
$^{137}\text{Cs}(1\text{MBq})\times 2$, Advanced Compton

Usual Compton Imaging (COMPTTEL)

Not using the electron tracks

- only event circle within ring form error region

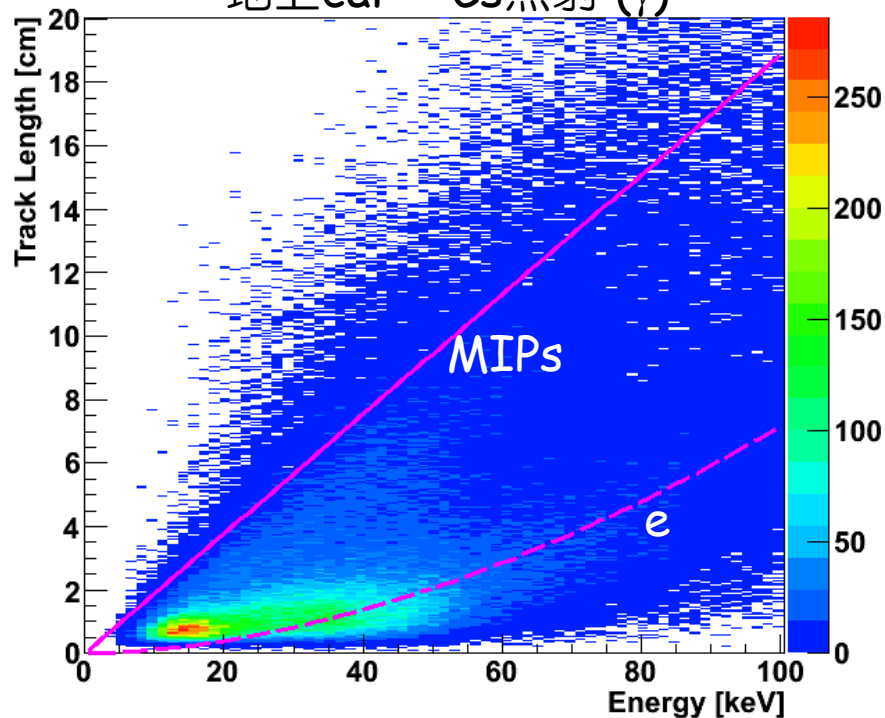
Simply overlay
Hard to separate
2 sources



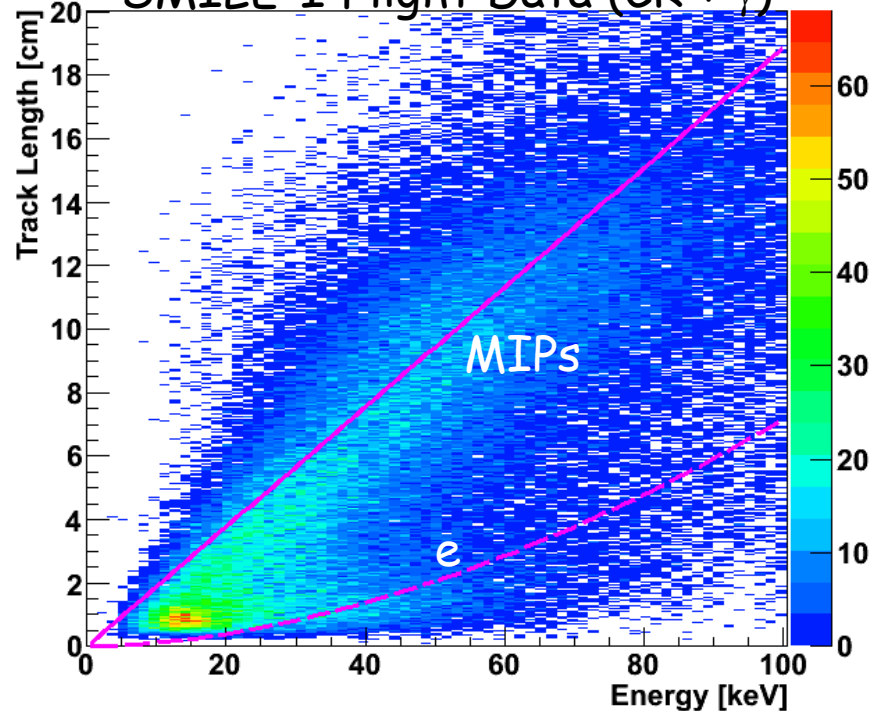
$^{137}\text{Cs}(1\text{MBq})\times 2$, usual Compton

Background rejection by TPC

地上cal ^{137}Cs 照射 (γ)

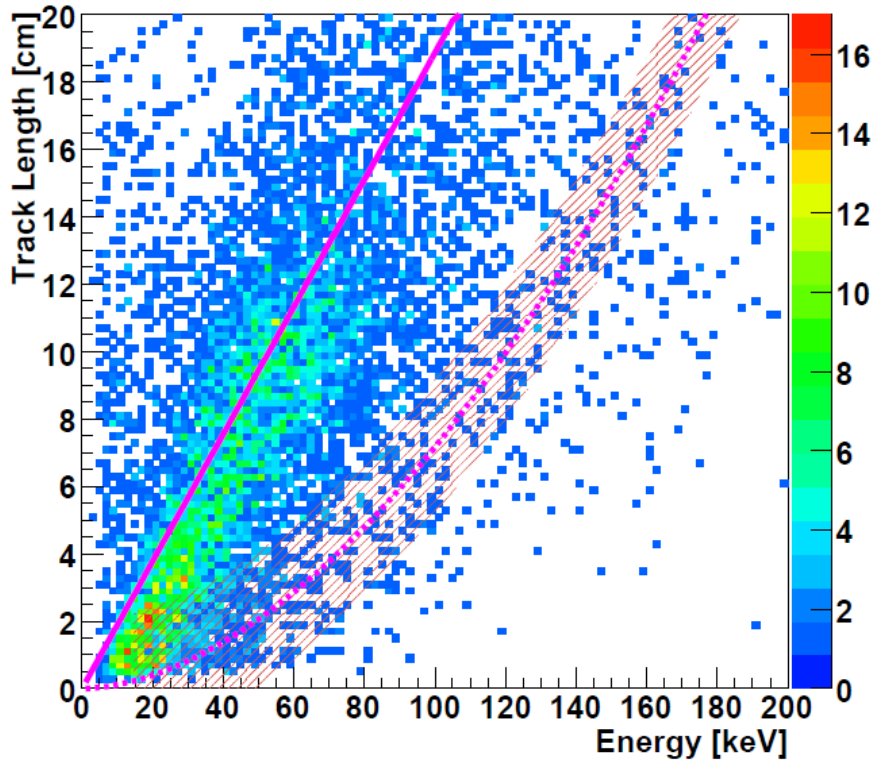


SMILE-I Flight Data (CR + γ)

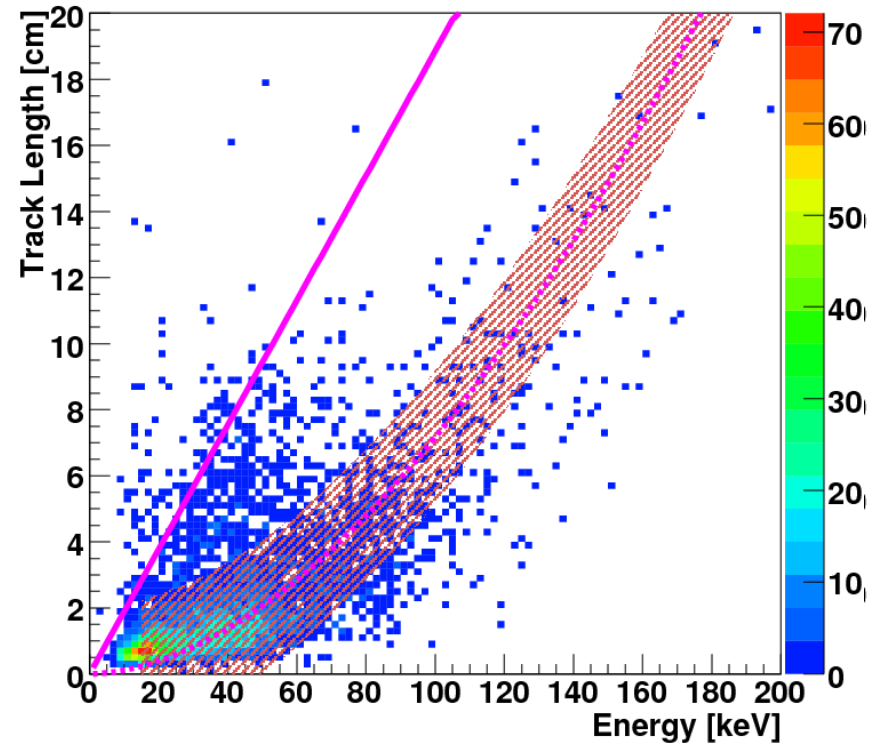


- TPCへのenergy depositとtrack lengthからparticle IDが可
- 電子と陽子の飛程の違い
 - ⇒ ガンマ線Compton散乱と中性子の弾性散乱の区別が容易

Background rejection by TPC



Charged particle mode



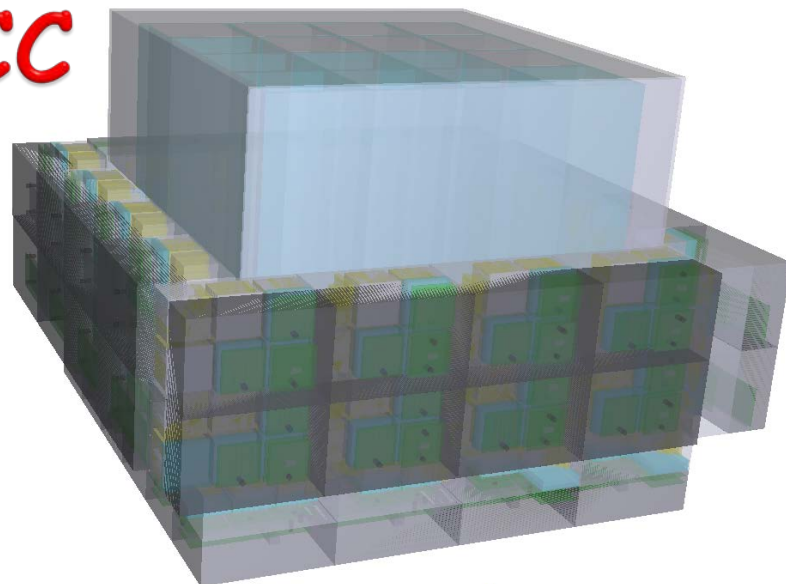
Compton mode

fiducial vol. = $7 \times 7 \times 7 \text{ cm}^3$

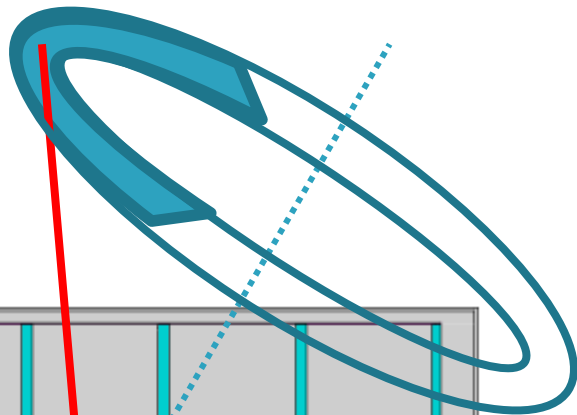
- TPCへのenergy depositとtrack lengthからparticle IDが可
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High Energy mode ETCC

電子吸収体をTPC中に導入することで
より高エネルギー側に感度を持たせる



Gaseous TPC



Electron-absorber

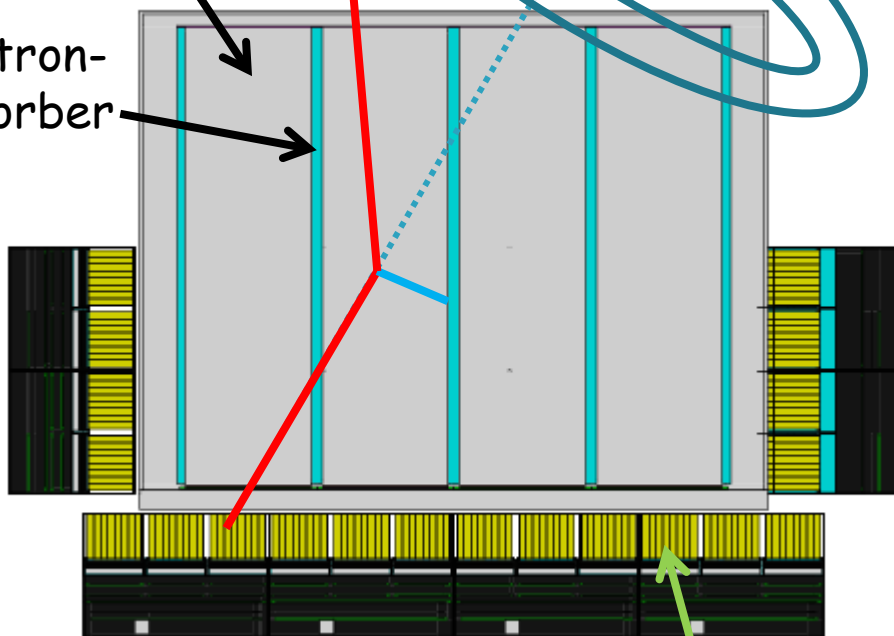
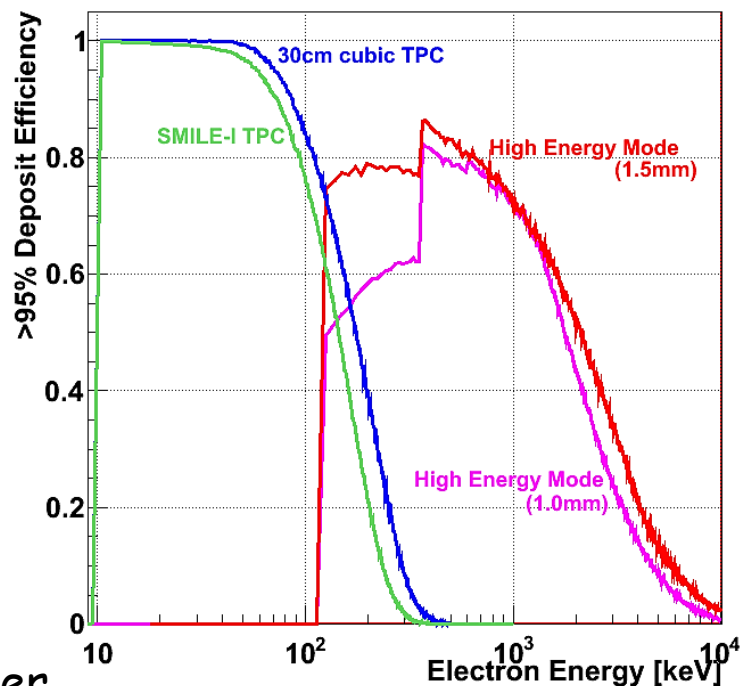
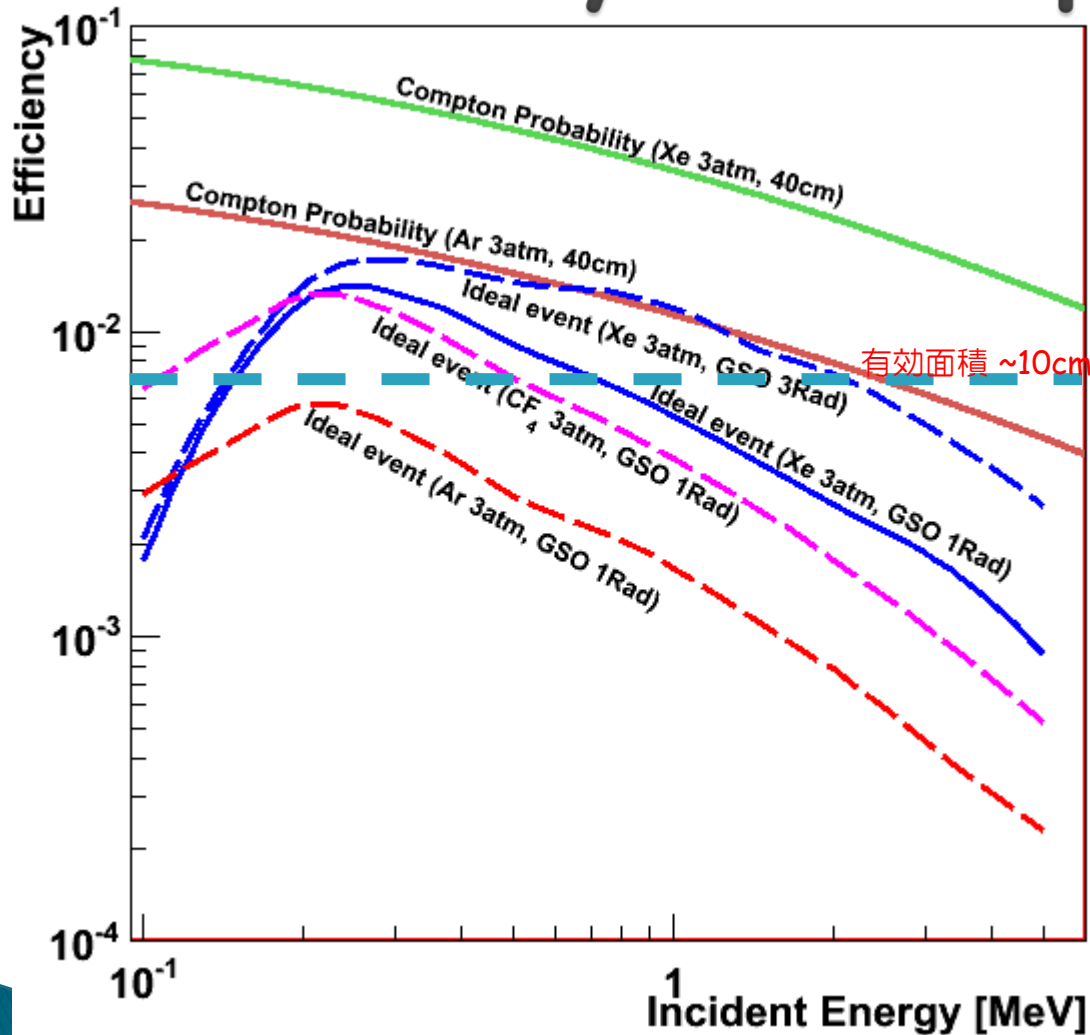


Photo-absorber



Efficiency of Compton event



Gas : Xe 3atm

TPC size : $(10 \times 10 \times 40 \text{ cm}^3) \times (4 \times 4)$

Electron-absorber:

plastic scinti. (1.02 g/cm^3)

GSO pixel : $6 \times 6 \times (13 \text{ or } 40) \text{ mm}^3$

Bottom : 96×96 pixel

Side : $(96 \times 32 \text{ pixel}) \times 4$

Detector responseは考慮せず

Xe 3atm + GSO 40mm

⇒ 検出器重量 ~250kg

結晶 200kg,

TPC他 50kg

Xe 3atm + GSO 13mm

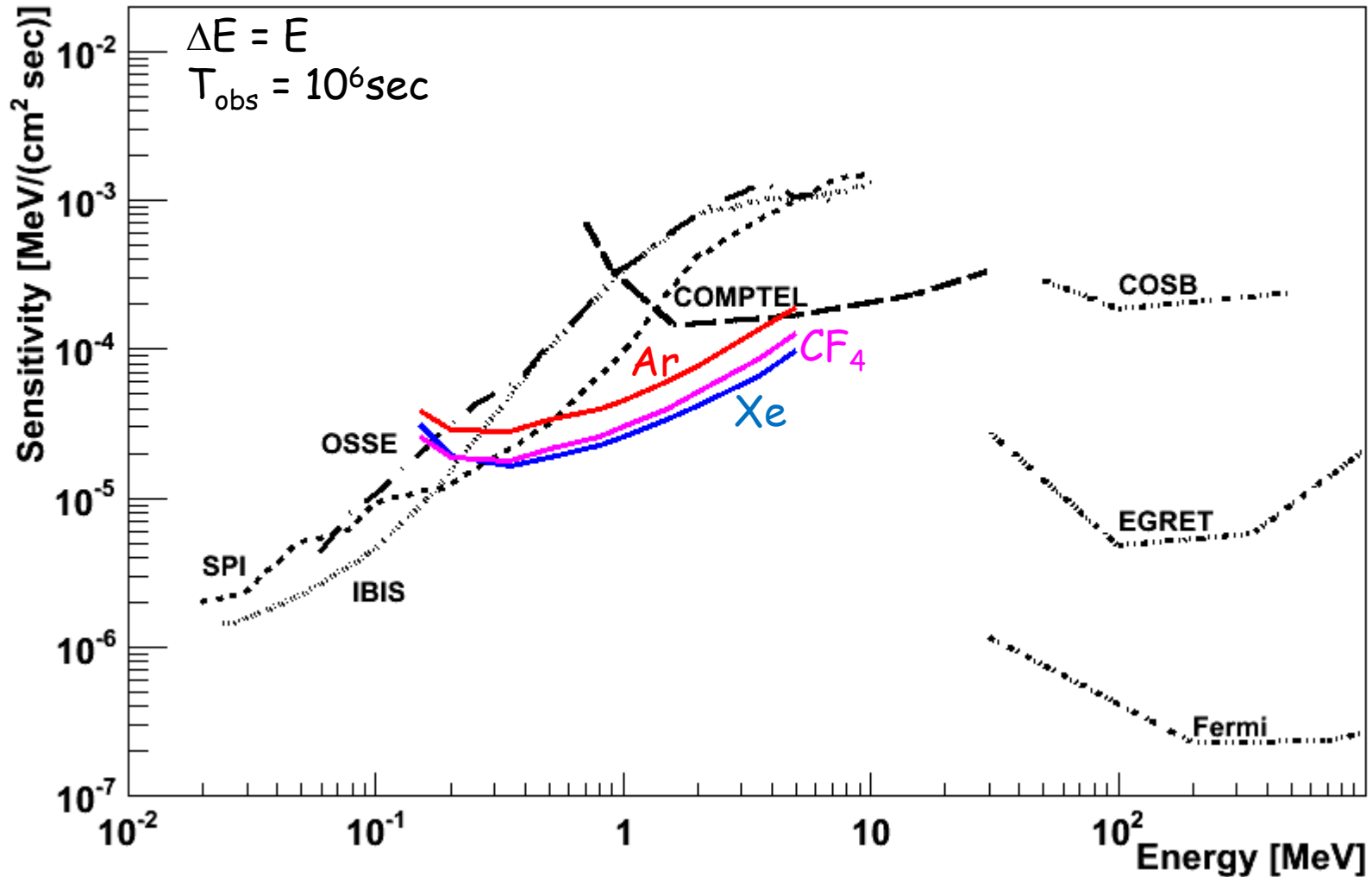
⇒ 検出器重量 ~120kg

結晶 70kg

TPC他 50kg

sensitivity

TPC : 10% @ 22keV
Scinti. : 3% @ 662keV
Detect of recoil dir. @ 5mm
Scattering angle < 90 deg



Plastic scinti.

TPC

GSO

preamp

NIM

VME

FPGA encoder

SMILE-I

開発現状

- 飛翔体観測に向け
省電力・省スペースなシステムの開発
- 電子飛跡の改善
- 有効面積の拡大
- 2回目の気球実験へ向けた準備

そのまま
拡大

40cm

40cm

Encoder (FPGA board)

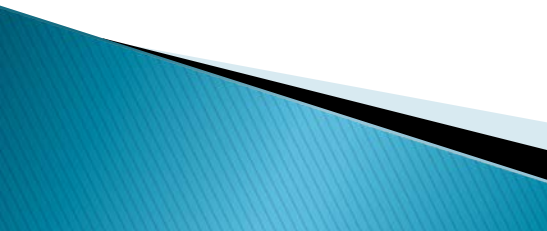
60cm

Gaseous TPC

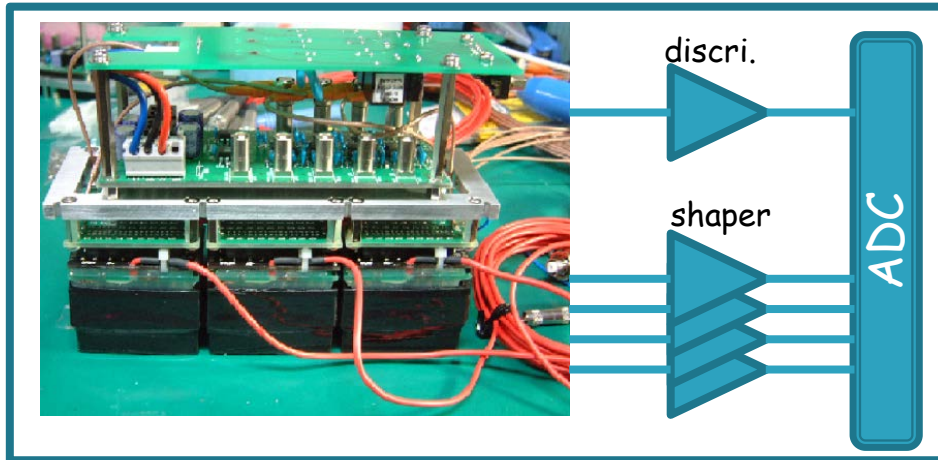
ASD (PreAmp)

Scintillation camera

30cm cube ETCC

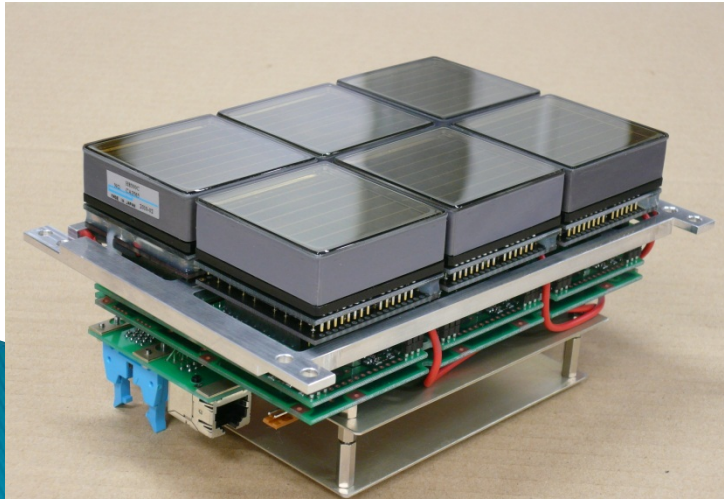


GSO readout system



SMILE-I GSO-PSA readout system

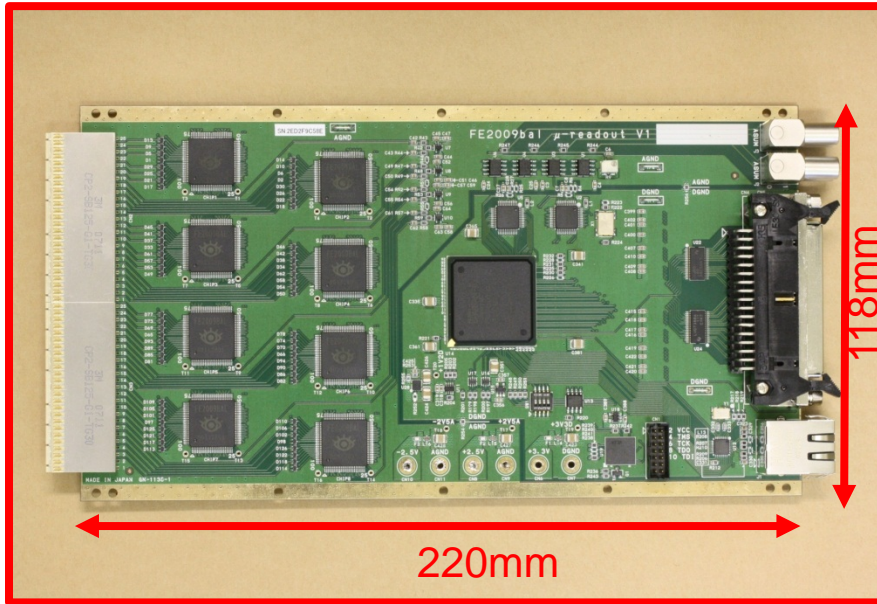
- 抵抗分割による読み出し
192 pixels/4 ch
- 消費電力 : 1.7 W/ch
- Energy分解能 : 11% @ 662keV
- Dynamic range : 80-800 keV
- NIM shaper + VME PHADC



SMILE-II Headamp unit system

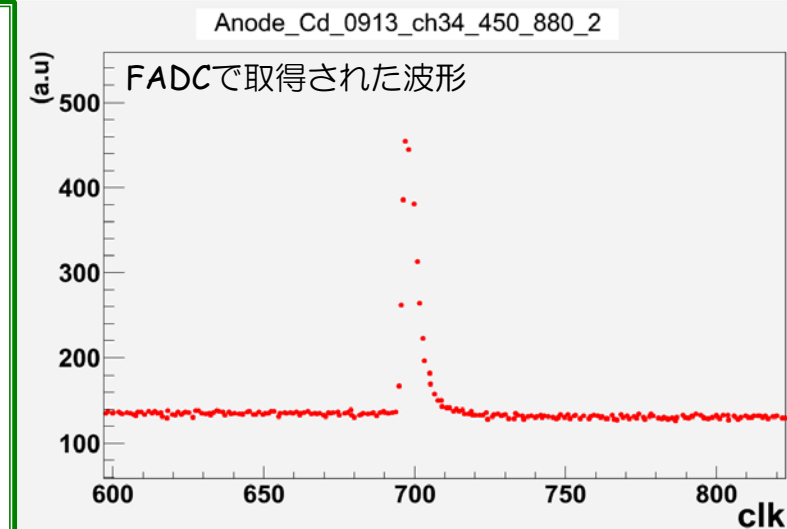
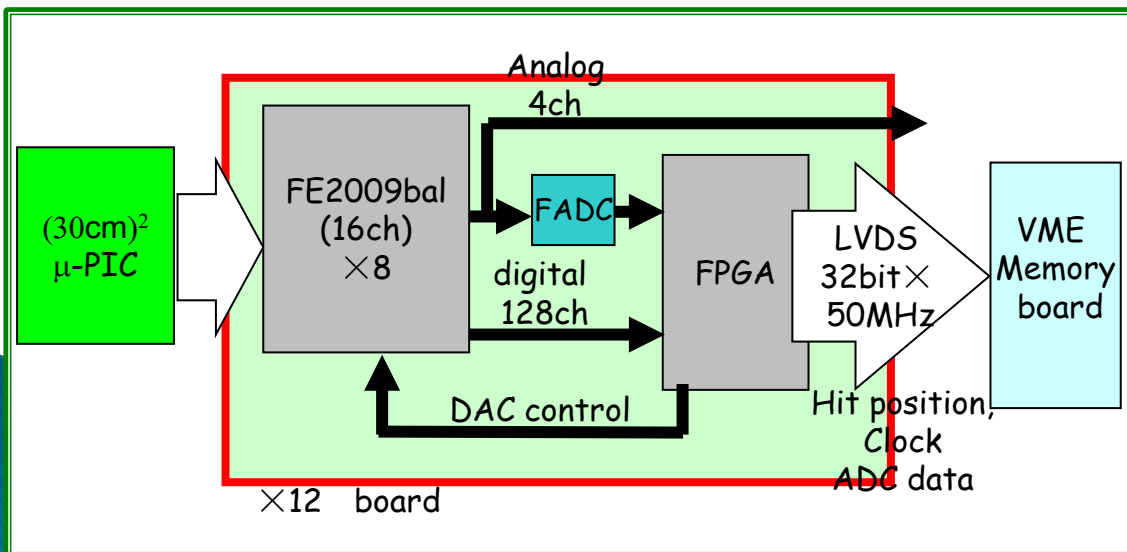
- 抵抗分割による読み出し
64 pixels/4 ch
- 消費電力 : 0.4 W/ch
- Energy分解能 : 10.3% @ 662keV
- Dynamic range : 80-1300 keV
- VME buffer board

TPC readout



Specification of Readout Board

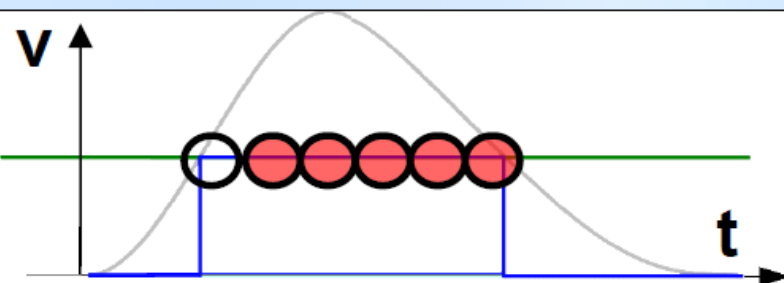
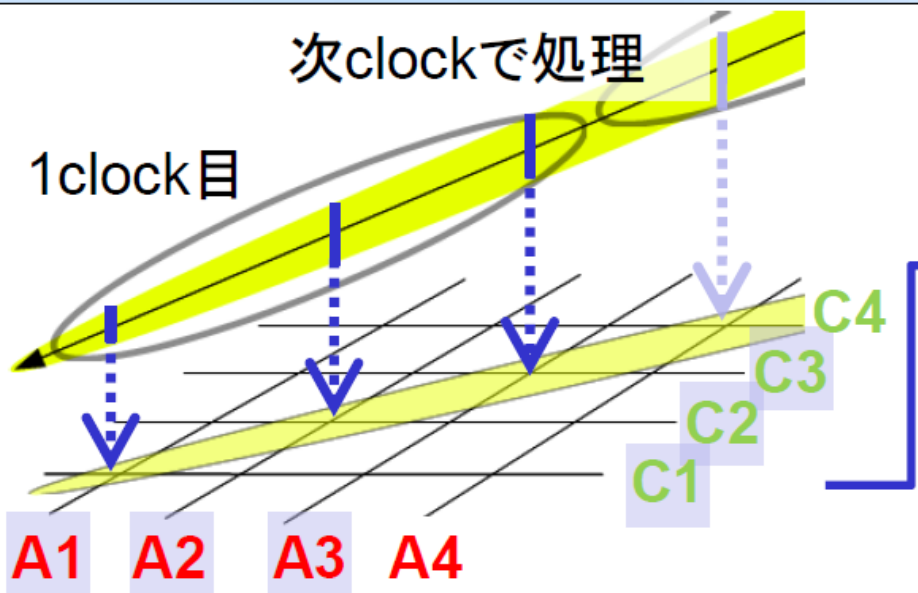
- 8 FE2009bal chips (128ch).
- 32ch sum analog signal output.
- 10bit 100MHz ADC \times 4.
- FPGA : Xilinx Spartan6
(XC6SLX100-2FGG676C).
- Parallel LVDS output
50MHz, 32bit (1.6Gbps).
- $\pm 2.5V$ and $+3.3V$ are required.
- Power Consumption : $\sim 5.5W$ /board.



改良した飛跡取得アルゴリズム

次clockで処理

1clock目



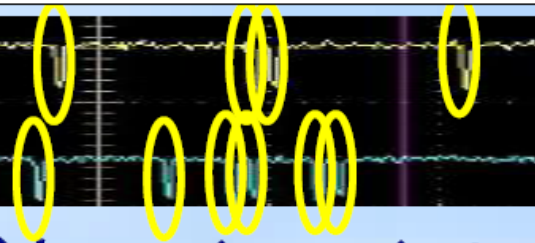
1、信号の立ち上がりを検出

2、10ナノ秒幅でHitしたストリップ番号の最大値と最小値を記録

3、10ナノ秒幅でAnode, Cathode Hitのコインシデンスをとる

Anode

Cathode



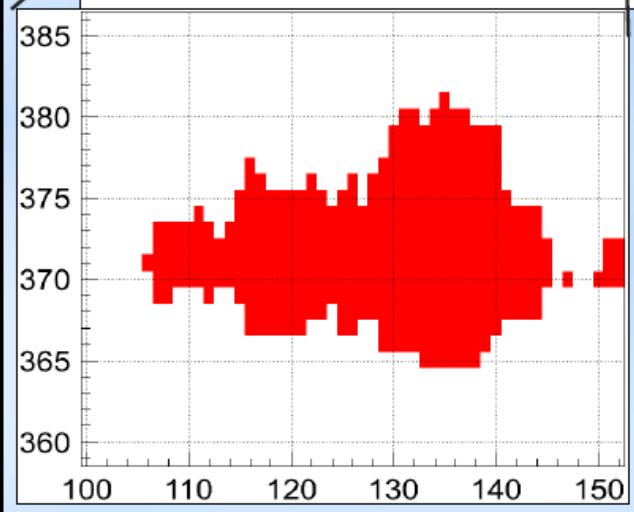
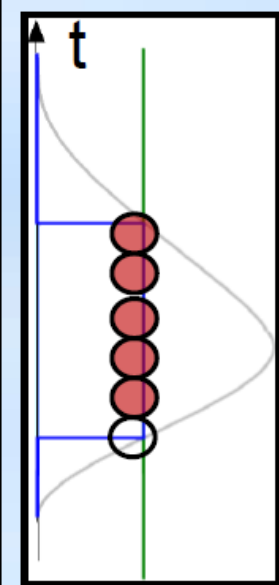
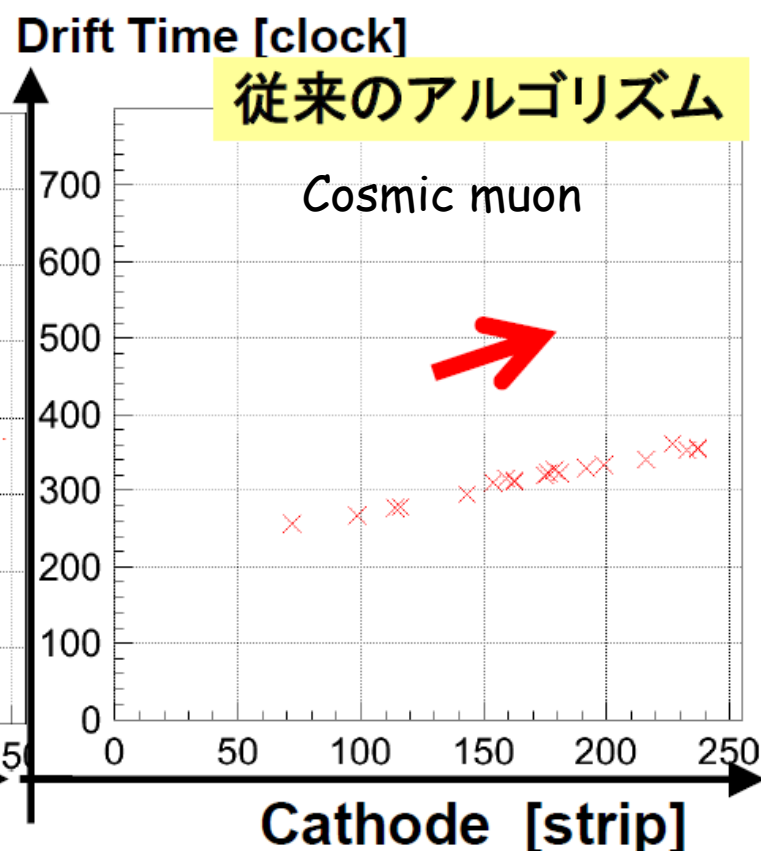
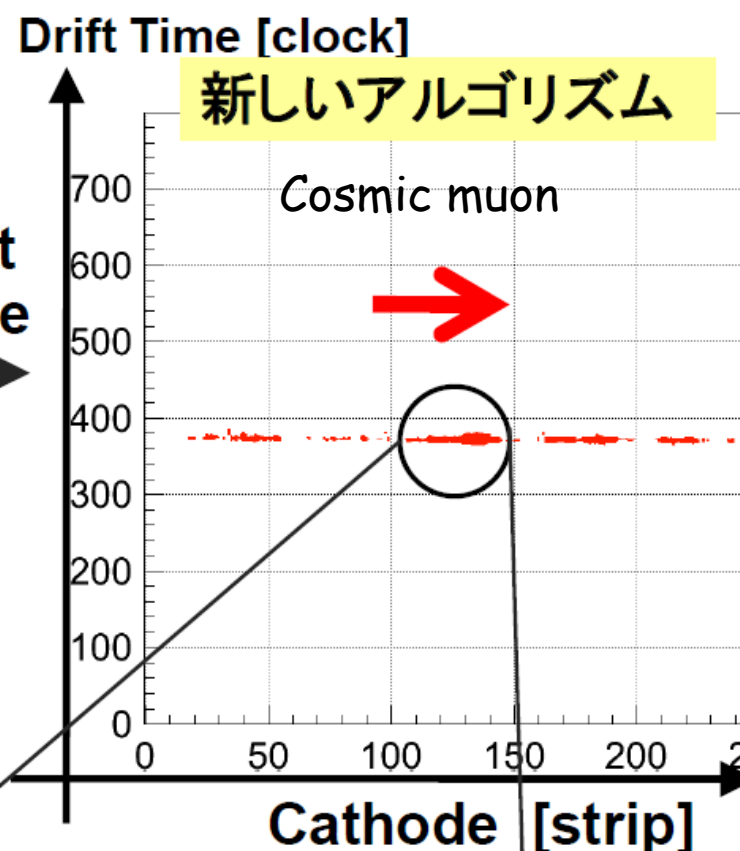
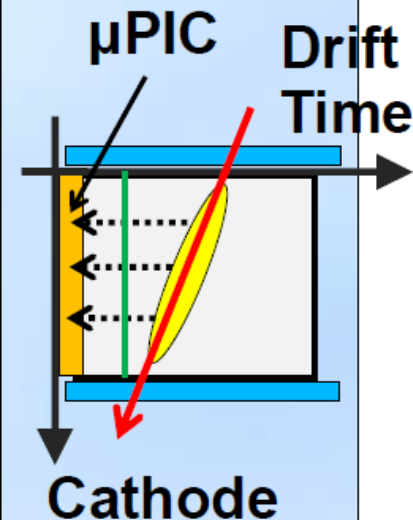
ハードウェア (FPGA) のプログラムを全面改訂した

1、スレッシュホールドを超えている間、検出を続ける

2、10ナノ秒幅でHitしたストリップ番号の**すべて**を記録

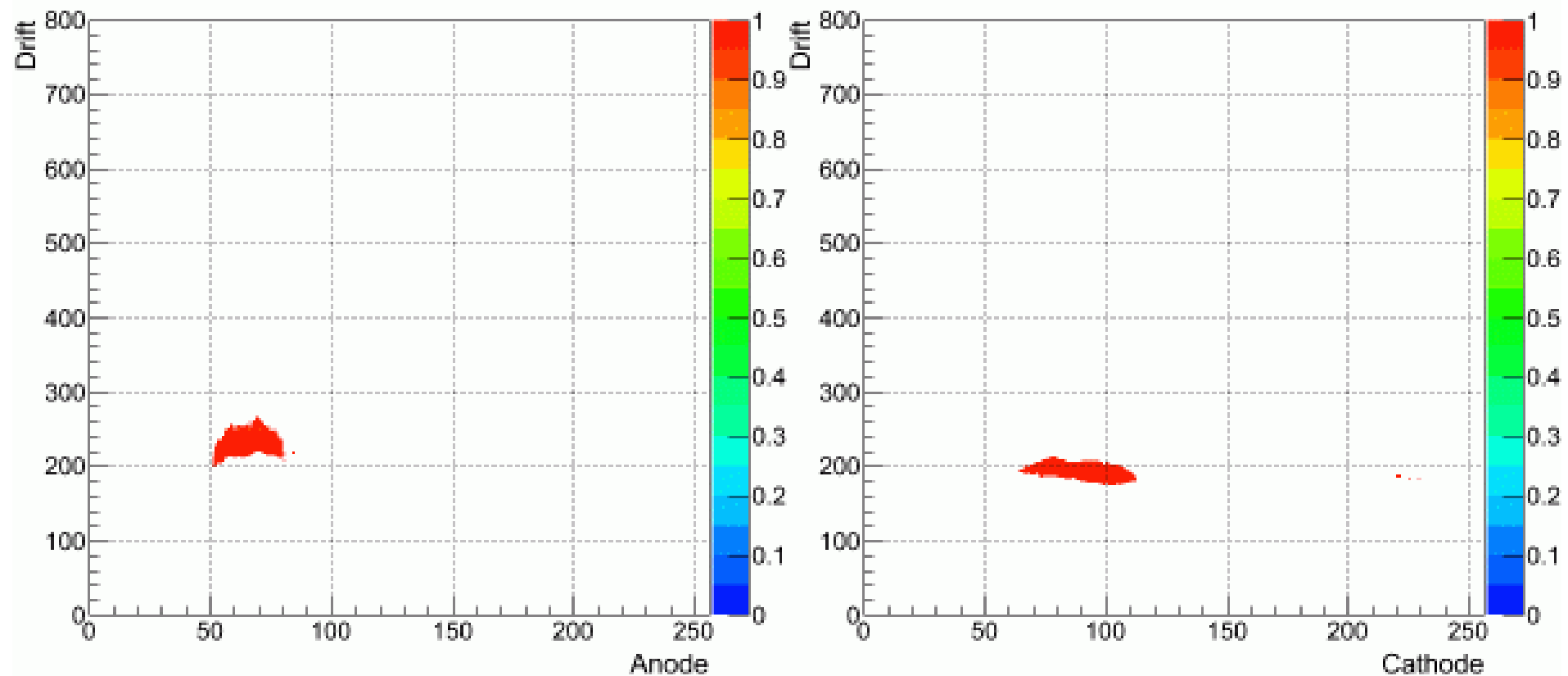
3、Anode, Cathode Hitの**コインシデンス**をとらず別々に記録

飛跡比較



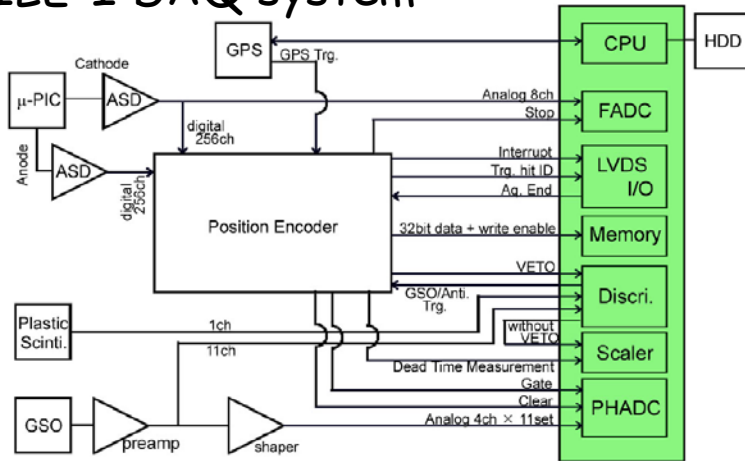
- ◆ μ PICに対して平行に近い飛跡
- ◆ データ点が密である
- ◆ Drift方向に幅をもつ
~信号のパルス幅

新しい手法で得られた電子飛跡



SMILE-II DAQ

SMILE-I DAQ system



SMILE-I DAQ

- Trigger後、CPUが全てのdataを取得
- CPUが取得中、ずっとVETO

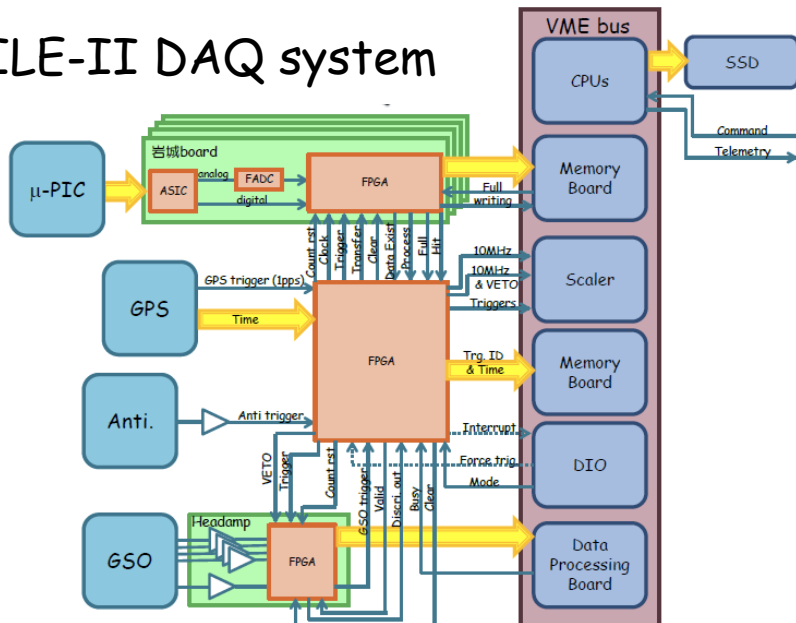


SMILE-II DAQ

- Trigger後、dataはbufferへ貯める
- Dataがbufferに移動したらVETO解除
- CPUはDAQに関係なくbufferのdataをstorageに保存するのみ



SMILE-II DAQ system



さらに将来のDAQ

- Trigger後、dataはnetwork上のstorageへ
- CPUは不要に

まとめ

- ▶ 電子飛跡検出型コンプトンカメラを開発中
- ▶ MeVガンマ線天文学の開拓を目的、
GRB探索にも可能性
- ▶ 飛翔体観測に向け、システム更新中
- ▶ 有効面積・角度分解能向上を狙った開発も進行中